

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No.:	10/611,480	Confirmation No. 3306
Applicant:	Sean Michael Malolepszy et al.	
Filed:	July 1, 2003	
TC/A.U.:	3729	
Examiner:	Arbes, Carl J	
Customer No.:	23494	
Docket:	TI-33434.1	

**EX PARTE QUAYLE AMENDMENT**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the Office action of February 22, 2006, applicants  
amend the application as follows:

**Amendments to the Specification** begins on page 2 of this paper.

**Amendments to the Claims**, as reflected in the listing of claims, begin on  
page 3 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.

Appl. No. 10/611,480  
Amdt. dated June 21, 2006  
Reply to Office action of Feb. 22, 2006

**Amendments to the Specification:**

Please replace the title of this application with the following new title:

Wirebonder to Bond an IC Chip to a Substrate

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:1.**

1-16. (canceled)

17. (original) A wirebonder adapted to wire bond an integrated circuit chip to a substrate, the substrate having formed thereon a plurality of conductive traces, at least one of the conductive traces having a bond region containing a bond surface, the machine comprising:

a support structure positioning device;

a conditioning device positioned adjacent the support structure positioning device, the conditioning device and the support structure being movable relative to one another in a direction normal to the support structure, the conditioning device comprising:

a member;

a raised boss on the member, the raised boss being configured to compress bond surfaces on a top surface of the support structure when the conditioning device is engaged with the support structure;

a cavity located so as to receive therein an integrated circuit chip mounted on said support structure when the flexible member is engaged with the support structure; and

a bond wire capillary positioned over the circuit board clamp.

18. (original) The machine of claim 17 further comprising a heater connected to the conditioning device.

19. (original) The machine of claim 17 further comprising a vibrator connected to the conditioning device.

20. (original) The machine of claim 17 further comprising a servo motor attached to the conditioning device, the servo motor moving the conditioning device relative the support structure positioning device.

**Remarks/Arguments**

Applicants thank Examiner Arbes for his careful examination of this application and for allowing claims 17-20. In response to the Office Action of February 22, 2006, applicants amend this application as follows:

1. The title of this application is changed to -- Wirebonder to Bond an IC Chip to a Substrate.
2. Claims 1-16 are canceled from this examination.

Applicants respectfully submit that as amended, this application is in allowable form.

Respectfully submitted,

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